Notification Number:	20151012000	Notification Date:	10/15/2015
Title:	Datasheet update for DAC3484		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			

☐	Assembly Site	☐	Design	☐	Wafer Bump Site
☐	Assembly Process	☒	Data Sheet	☐	Wafer Bump Material
☐	Assembly Materials	☐	Part number change	☐	Wafer Bump Process
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Site
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
				☐	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification.

The product datasheet(s) is updated as seen in the change revision history below:

TEXAS INSTRUMENTS

DAC3484

SLAS749D – MARCH 2011 – REVISED SEPTEMBER 2015 www.ti.com

Changes from Revision C (August 2012) to Revision D **Page**

- Added *ESD Ratings* table, *Feature Description* section, *Device Functional Modes, Application and Implementation* section, *Power Supply Recommendations* section, *Layout* section, *Device and Documentation Support* section, and *Mechanical, Packaging, and Orderable Information* section. 1
- Added 196-ball 12x12mm BGA package to Description 1
- Added additional operation requirement for SLEEP pin if SLEEP pin is set to logic HIGH before and during device power up and initialization. 7
- Added additional circuit configuration for unused terminals - IOUTAP/N, IOUTBP/N, IOUTCP/N, IOUTDP/N 9
- Added additional operation requirement for SLEEP pin if SLEEP pin is set to logic HIGH before and during device power up and initialization. 10
- Changed DACCLKP/N Differential voltage TYP value from 1.0 V to 0.8 V 14
- Changed the parameter name Single-Ended Swing Level to Single-Ended Input Level to better reflect the specification for minimum recommended single-ended voltage level. 14
- Changed OSTRP/N Differential voltage TYP value from 1.0 V to 0.8 V 14
- Changed the parameter name Single-Ended Swing Level to Single-Ended Input Level to better reflect the specification for minimum recommended single-ended voltage level. 14
- Changed Standard high swing note for *Electrical Characteristics – Digital Specifications* 14
- Added Minimum voltage note for *Electrical Characteristics – Digital Specifications* 14
- Added LMK0480x family to note for *Timing Requirements – Digital Specifications* 16
- Added text to Input FIFO section 32
- Changed syncsel_fifoout(3:0) description in Input FIFO section to clarify the FIFO read pointer reset capture method and limitation 33
- Added Note to Input FIFO section 33
- Added LMK0480x family to Input FIFO section 33
- Changed text in Single Sync Source Mode to clarify the latency limitation of Single Sync Source Mode 35
- Added the effect of bypassing the FIFO in the Bypass Mode section to clarify the operation of the FIFO, LVDS

The datasheet number will be changing.

Device Family	Change From:	Change To:
DAC3484	SLAS749C	**SLAS749D**

These changes may be reviewed at the datasheet links provided.

http://www.ti.com/product/dac3484

Reason for Change:

To more accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this Notification:

None.

Product Affected:

DAC3484IRKD25	DAC3484IRKDT	DAC3484IZAYR
DAC3484IRKDR	DAC3484IZAY	

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
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Asia Pacific	PCNAsiaContact@list.ti.com
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